

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/06/2022

Details for "SN74AVC2T244DQER"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
SN74AVC2T244DQER	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DQE   8	1.4x1x0.37	1.2

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.024492	100	1000000	2.052983	20530
Sub-Total			0.024492	100	1000000	2.052983	20530
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.007027	29.999146	299991	0.589021	5890
Other Inorganic Materials	Silica	7631-86-9	0.001054	4.499658	44997	0.088349	883
Other Organic Materials	Chlorine	7782-50-5	0.000008	0.034153	342	0.000671	7
Thermoplastics	Epoxy	85954-11-6	0.015335	65.467042	654670	1.285419	12854
Sub-Total			0.023424	100	1000000	1.96346	19635
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	0.39195	97.5	975000	32.854259	328543
Magnesium and Its Alloys	Magnesium	7439-95-4	0.00201	0.05	500	0.016848	168
Nickel and Its Alloys	Nickel	7440-02-0	0.008844	2.2	22000	0.741327	7413
Other Inorganic Materials	Silicon	7440-21-3	0.001005	0.25	2500	0.084242	842
Sub-Total			0.402	100	1000000	33.696676	336967
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.013622	97.3	973000	1.141831	11418
Precious Metals	Gold	7440-57-5	0.000042	0.3	3000	0.003521	35
Precious Metals	Palladium	7440-05-3	0.000294	2.1	21000	0.024644	246
Precious Metals	Silver	7440-22-4	0.000042	0.3	3000	0.003521	35
Sub-Total			0.014	100	1000000	1.173516	11735
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	0.551007	84.399987	844000	46.186827	461868
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.034079	5.220019	52200	2.85659	28566
Other Plastics and Rubber	Carbon Black	1333-86-4	0.001175	0.17998	1800	0.098492	985
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.000588	0.090066	901	0.049288	493
Thermoplastics	Epoxy	85954-11-6	0.066003	10.109948	101099	5.532542	55325
Sub-Total			0.652852	100	1000000	54.723738	547237
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.076228	100	1000000	6.389627	63896
Sub-Total			0.076228	100	1000000	6.389627	63896
<b>Total</b>			1.192996			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.